

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Aug 24, 2013 01:49 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
1N916	1N916	DO-35 (Glass)			SUBCONTRACTOR	0.110000	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Alloy 42	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom
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RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted
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Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU	7(c)-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g piezoelectronic dev
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Declaration Signature	
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Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DO-35 (Glass)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
CSS Wire	Other Ferrous alloys, non-stainless steels	75.025	Supplier		Carbon	0.375	7440-44-0	3409
			Supplier		Copper	26.300	7440-50-8	239091
			Supplier		Iron	48.200	7439-89-6	438182
			Supplier		Manganese	0.150	7439-96-5	1364
Chip	Other inorganic materials	0.021	Supplier		Silicon	0.021	7440-21-3	188
Dumet Wire	Other Ferrous alloys, non-stainless steels	8.491	Supplier		Carbon	0.013	7440-44-0	116
			Supplier		Cobalt	0.043	7440-48-4	386
			Supplier		Copper	1.910	7440-50-8	17364
			Supplier		Iron	3.730	7439-89-6	33909
			Supplier		Manganese	0.010	7439-96-5	93
			B	Nickel (external applications only)	Nickel	2.760	7440-02-0	25091
			Supplier		Silicon	0.026	7440-21-3	232
Encapsulation	Ceramics / Glass	23.468	Supplier		Antimony trioxide	0.012	1309-64-4	107
			Supplier		Diboron Trioxide *	0.705	1303-86-2	6409
			A	Lead/Lead Compounds	Lead (II,IV) oxide	14.300	1314-41-6	130000
			Supplier		Potassium Oxide	0.881	12136-45-7	8009
			Supplier		Silicon Dioxide, quartz	7.570	14808-60-7	68818
Ink	Marking Ink	0.021	Supplier		2,2,4-Trimethyl-1,3-pentanediol di isobutyrate	0.002	6846-50-0	16
			Supplier		Amino Resin	0.004	68002-20-0	36
			Supplier		C.I. pigment Violet	0.001	6358-30-1	6
			Supplier		C.I. pigment blue	0.001	147-14-8	5
			Supplier		Carbon Black	0.003	1333-86-4	25
			Supplier		Diethylene glycol 2-ethyhexyl-ether	0.004	1559-36-0	32
			Supplier		Ethene, Homopolymer	0.000	9002-88-4	3
			Supplier		Phenolic Resin	0.007	25085-75-0	61
Plating	Other Nonferrous metals & alloys	2.630	Supplier		Tin	2.630	7440-31-5	23909